## **Listing of Claims:**

- 1. (Currently Amended) A method of depositing material on a substrate layer, comprising the steps of:
  - (a) forming a multilayered structure, said forming comprising:
    - (i) coating said substrate layer with a spacer/pattern layer; and
    - (ii) pressing a cover layer against said spacer/pattern layer;
  - (b) dipping said multilayered structure into solution containing said material for a sufficient length of time to allow said solution to spread through capillary action to a predetermined region defined by said spacer/pattern layer; and
  - (c) removing said cover layer from said spacer/pattern layer, leaving behind said substrate layer coated with said spacer/pattern layer and said solution spread to said predetermined region defined by said spacer/pattern layer;

wherein a stacked layer is formed by repeating step (b) with a different solution containing a different material, before removal of said cover layer, or by after step (c), repeating steps (a)(ii), (b) and (c) with a different solution containing a different material.

2. (Previously Presented) The method of depositing material on a substrate layer of claim 1, wherein said coating comprises: placing said spacer/pattern layer on said substrate layer; and selectively removing portions of said spacer/pattern layer to define said predetermined region such that at least one channel is formed along at least one edge of said spacer/pattern layer.

3. (Withdrawn) An OLED (organic light emitting diode), wherein at least part of said OLED is manufactured using the method of depositing material on a substrate layer of claim 1.

## 4. (Canceled)

5. (Withdrawn) An OLED, wherein at least part of said OLED is manufactured using the method of depositing a plurality of materials on a substrate layer of claim 4.

## 6. (Canceled)

- 7. (Withdrawn) An OLED, wherein at least part of said OLED is manufactured using the method of depositing a plurality of materials on a substrate layer of claim 6.
- 8. (Currently Amended) A method of depositing a first material and a second material on a substrate layer, comprising the steps of:
  - (a) forming a first multilayered structure, said forming comprising:
    - (i) coating said substrate layer with a spacer/pattern layer, wherein said spacer/pattern layer defines a first region and a separate second region; and
    - (ii) pressing a first cover layer against said spacer/pattern layer;
  - (b) dipping said first multilayered structure into a first solution containing said first material for a sufficient length of time to allow said first solution to spread through capillary action to said first region;

- (c) removing said cover layer from said spacer/pattern layer, leaving behind said substrate layer coated with said spacer/pattern layer and said solution spread to said predetermined region defined by said spacer/pattern layer;
- (d) pressing a second cover layer against said spacer/pattern layer to form a second multilayered structure;
- (e) dipping said second multilayered structure into a second solution containing said second material for a sufficient length of time to allow said second solution to spread through capillary action to said second region; and
- (f) removing said second cover layer from said spacer/pattern layer, leaving behind said substrate layer coated with said spacer/pattern layer and said solution spread to said predetermined region defined by said spacer/pattern layer;

wherein a stacked layer is formed by repeating step (b) with a different first solution containing a different first material and step (e) with a different second solution containing a different second material, before removal of said cover layer, or by, after step (c), repeating steps (a)(ii), (b) and (c) with a different first solution containing a different first material and, after step (f), repeating steps (d), (e) and (f) with a different second solution containing a different second material.

9. (Previously Presented) The method of depositing a first material and a second material on a substrate layer of claim 8, wherein said coating comprises:

placing said spacer/pattern layer on said substrate; and

selectively removing portions of said spacer/pattern layer to define said first region and said separate second region such that at least one channel is formed along at least one edge of said spacer/pattern layer.

- 10. (Original) The method of depositing a first material and a second material on a substrate layer of claim 8, wherein said second cover layer is said first cover layer and said second multilayered structure is said first multilayered structure.
- 11. (Withdrawn) An OLED, wherein at least part of said OLED is manufactured using the method of depositing a first material and a second material on a substrate layer of claim 8.
- 12. (Previously Presented) The method of depositing a first material and a second material on a substrate layer of claim 8, further comprising the steps of:
  - (g) pressing a third cover layer against said spacer/pattern layer to form a third multilayered structure;
  - (h) dipping said third multilayered structure into a third solution containing said third material for a sufficient length of time to allow said third solution to spread through capillary action to said third region; and
    - (i) removing said third cover layer from said spacer/pattern layer.
- 13. (Withdrawn) A multilayered structure for depositing material on a substrate layer, comprising:
  - (a) said substrate layer;

- (b) a spacer/pattern layer coating said substrate layer, wherein said spacer/pattern layer defines at least one region having at least one conduit for drawing in solution containing said material by way of capillary action; and
  - (c) a cover layer pressed against said spacer/pattern layer.
- 14. (Withdrawn) The multilayered structure for depositing material on a substrate layer of claim 13, wherein said at least one region is a plurality of regions, each one of said plurality of regions having a separate said at least one conduit.

## 15. (Canceled)

- 16. (Withdrawn) The multilayered structure for depositing material on a substrate layer of claim 14, wherein each of said plurality of regions has a different pattern, wherein at least one of said plurality of regions has a pattern comprising lines.
- 17. (Withdrawn) The multilayered structure for depositing material on a substrate layer of claim 14, wherein each of said plurality of regions has a different pattern, wherein at least one of said plurality of regions has a pattern comprising icons.
- 18. (Currently Amended) A method of depositing material on a substrate layer, comprising the steps of:
  - (a) forming a multilayered structure, said forming comprising:
    - (i) coating said substrate layer with a first part of a spacer/pattern layer; and

- (ii) pressing a cover layer attached to a remaining part of said spacer/pattern layer against said first part of said spacer/pattern layer to form a complete said spacer/pattern layer;
- (b) dipping said multilayered structure into solution containing said material for a sufficient length of time to allow said solution to spread through capillary action to a predetermined region defined by said spacer/pattern layer; and
- (c) removing said cover layer from said first part of a spacer/pattern layer, leaving behind said substrate layer coated with said spacer/pattern layer and said solution spread to said predetermined region defined by said spacer/pattern layer;

wherein a stacked layer is formed by repeating step (b) with a different solution containing a different material, before removal of said cover layer, or by, after step (c), repeating steps (a)(ii), (b) and (c) with a different solution containing a different material.

- 19. (Previously Presented) The method of depositing material on a substrate layer of claim 1, wherein said material comprises light emitting polymers or conducting polymers.
- 20. (Previously Presented) The method of depositing a first material and a second material on a substrate layer of claim 8, wherein said material and said second material comprise light emitting polymers or conducting polymers.
- 21. (Previously Presented) The method of depositing material on a substrate layer of claim 18, wherein said material comprises light emitting polymers or conducting polymers.